Abstract

The invention relates to a device for bonding of one bond side of a first substrate to one bond side of a second substrate with the following features:

- one module group (9) with a common working space which can be closed especially gastight to the vicinity,
- at least one bond module (5) of the module group (9), which module is connected, especially in a sealed manner, to the working space,
- a movement apparatus for moving the first and second substrate in the working space,

characterized in that the module group (9) has a reduction module (4) which is connected, especially in a sealed manner, to the working space for reducing the bond sides. Furthermore the invention relates to a corresponding method with the following progression:

- reducing the bond sides in a reduction module of the module group (9) connected to the working space,
- moving the first and second substrate in the working space from the reduction module in a bond space of a bond module (5) of the module group (9) and
- bonding of the first substrate to the second substrate on the bond sides.

Figure 1 in this respect